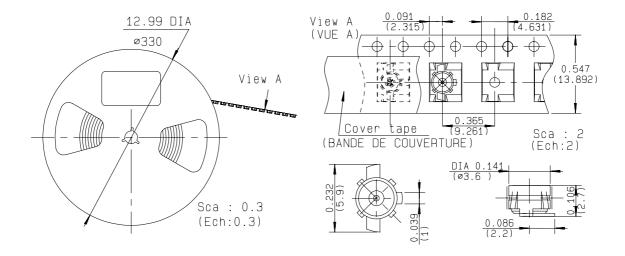
SMT TYPE - GOLD 0.2 - REEL OF 500

R210.408.052

Series: MMT



All dimensions are in mm.



 COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	PHOSPHOR BRONZE BRASS PHOSPHOR BRONZE PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.2 OVER NICKEL 2 GOLD 0.2 OVER NICKEL 2
	I	

Issue: 0325 A

In the effort to improve our products, we reserve the right to make changes judged to be



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Series: MMT

PACKAGING

Standard	Unit	Other
500	•	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance **50** Ω Frequency **0-8** GHz

VSWR 1.10 + **0.050** x F(GHz) Maxi

Insertion loss **0.20** $\sqrt{F(GHz)}$ dB Maxi RF leakage **NA** - F(GHz)) dB Maxi - (

Voltage rating 170 Veff Maxi Dielectric withstanding voltage **500** Veff mini Insulation resistance **5000** MΩ mini

ENVIRONMENTAL

Operating temperature -55/+100 ° C

Hermetic seal NA Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

accouplt: 18Nmax / desacc.: 7Nmin

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end NA N mini Axial force – Opposite end NA N mini Torque NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life **500** Cycles mini

Weight **0.100** g

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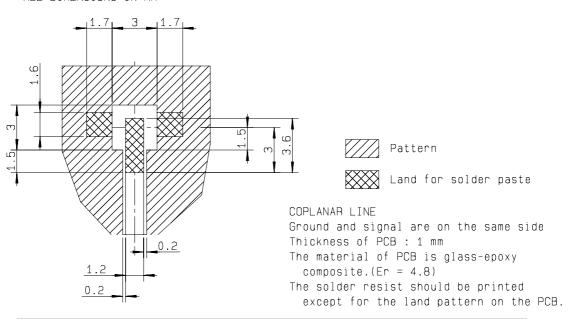
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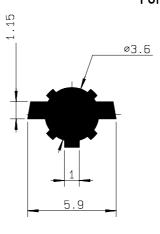
MMT SERIES - INFORMATION

ALL DIMENSIONS IN MM



ALL DIMENSIONS IN MM

SHADOW OF MMT RECEPTACLE FOR VIDEO CAMERA



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SMT TYPE - GOLD 0.2 - REEL OF 500

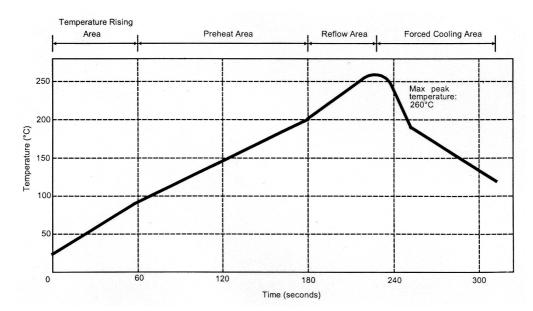
R210.408.052

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SOLDER PROCEDURE OF MMT RECEPTACLE IN INDUSTRIAL ENVIRONMENT

- 1-Deposition of solder paste Sn Ag4 Cu0.5 on mounting zone by screen printing application. We recommend a Low Residue Solid Flux.
 - We advise a thickness of 200 microns (7.800 microinches). Verify that the edges of the prined zone are clean.
- 2 Placement of the receptacle on the mounting zone with an automatic machine of « pick and place » type. A video camera is recommanded for positioning of the component. (see page 3) Adhesive agents must not be used on the receptacle.
- 3 Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4 Cleaning of printed circuit boards
- 5 Verification of solder joints and position of the component by visual inspection

Note: The MMT receptacle and the MMT plug must not be mated before completion of this procedure.



Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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necessary.

